CLAIMS

What is claimed is:

1. An integrated circuit package, comprising:

a substrate;

an integrated circuit mounted to said substrate;

a thermal element located adjacent to said integrated circuit; and,

an epoxy that is attached to said integrated circuit and said thermal element, said epoxy being cured by energy at a microwave frequency.

2. The package of claim 1, further comprising a solder ball attached to said substrate.

3. The package of claim 1, further comprising a solder bump attached to said integrated circuit and said substrate.

4. The package of claim 1, further comprising an encapsulant that encloses said integrated circuit.

5. A method for assembling an integrated circuit package, comprising:

applying an epoxy to an integrated circuit;

placing a thermal element adjacent to the epoxy; and,

curing the epoxy with energy at a microwave frequency.

6. The method of claim 5, further comprising the step of mounting the integrated circuit to a substrate.

7. The method of claim 6, further comprising the step of attaching a solder ball to the substrate.

8. The method of claim 5, further comprising the step of molding an encapsulant onto the substrate and the integrated circuit.

9. A method for assembling an integrated circuit package, comprising:

applying an epoxy to a thermal element;

placing the epoxy and the thermal element onto an integrated circuit; and,

curing the epoxy with energy at a microwave frequency.

Sub A3 10. The method of claim 9, further comprising the step of mounting the integrated circuit to a substrate.

Sub A4 11. The method of claim 10, further comprising the step of attaching a solder ball to the substrate.

Sub A5

12. The method of claim 9, further comprising the step of molding an encapsulant onto the substrate and the integrated circuit.

Add A6